

TC74HC107AP, TC74HC107AF, TC74HC107AFN

DUAL J-K FLIP FLOP WITH CLEAR

The TC74HC107A is a high speed CMOS DUAL J-K FLIP FLOP fabricated with silicon gate C²MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

In accordance with the logic levels applied to the J and K inputs, the outputs change state on the negative going transition of the clock pulse.

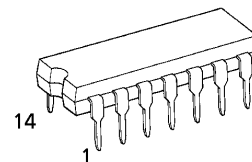
$\overline{\text{CLR}}$ is independent of the clock and is accomplished by a low logic level on the input.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

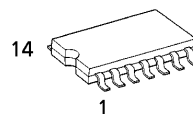
FEATURES:

- High Speed..... $f_{\text{MAX}} = 75\text{MHz}$ (typ.)
at $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 2\mu\text{A}$ (Max.) at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}}$ (Min.)
- Output Drive Capability.....10 LSTTL Loads
- Symmetrical Output Impedance... $|I_{\text{OH}}| = I_{\text{OL}} = 4\text{mA}$ (Min.)
- Balanced Propagation Delays..... $t_{\text{PLH}} \approx t_{\text{PHL}}$
- Wide Operating Voltage Range... V_{CC} (opr.) = $2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS107

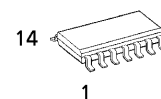
(Note) The JEDEC SOP (FN) is not available in Japan.



P (DIP14-P-300-2.54)
Weight : 0.96g (Typ.)

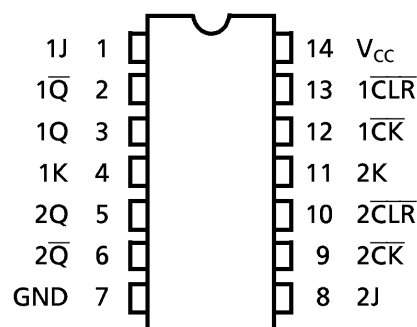


F (SOP14-P-300-1.27)
Weight : 0.18g (Typ.)



FN (SOL14-P-150-1.27)
Weight : 0.12g (Typ.)

PIN ASSIGNMENT



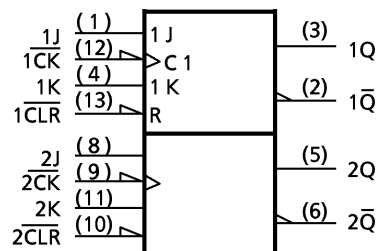
(TOP VIEW)

TRUTH TABLE

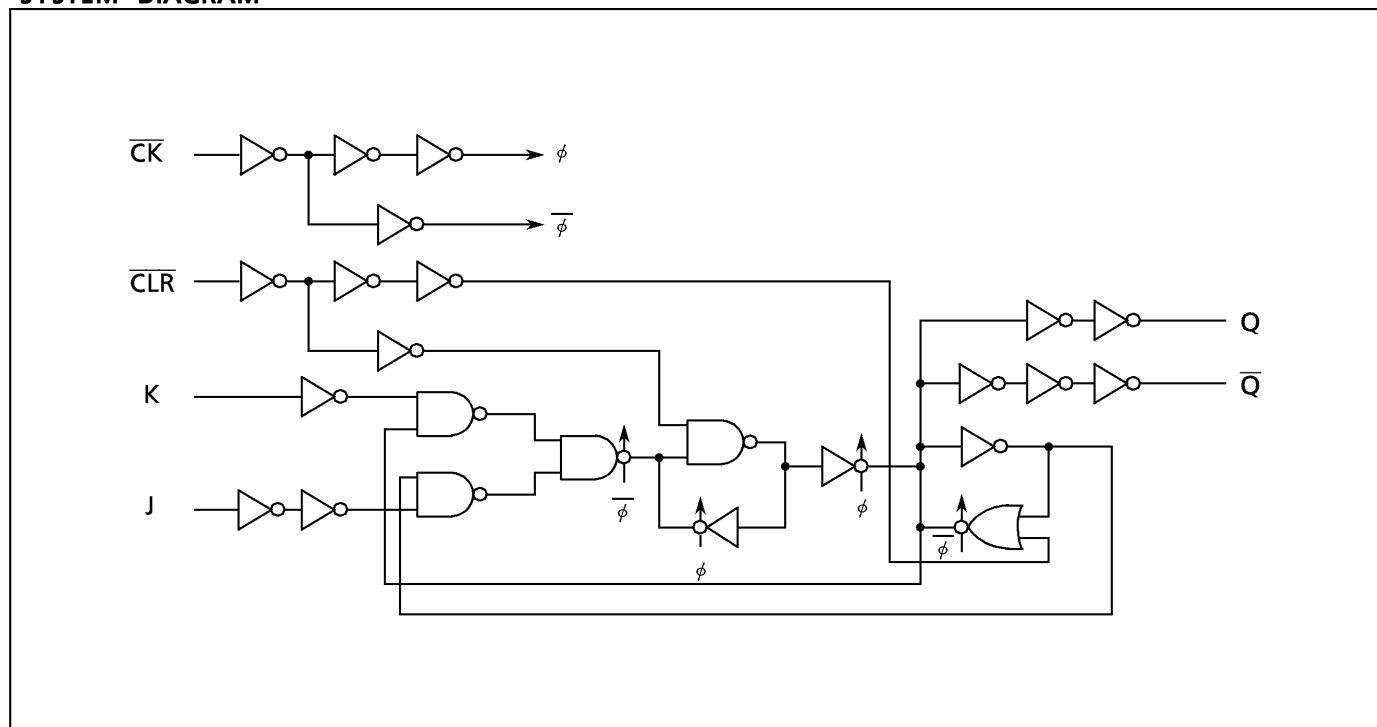
INPUTS				OUTPUTS		FUNCTION
CLR	J	K	CK	Q	Q-bar	
L	X	X	X	L	H	CLEAR
H	L	L	$\downarrow$	Q_n	$\overline{Q}_n$	NO CHANGE
H	L	H	$\downarrow$	L	H	—
H	H	L	$\downarrow$	H	L	—
H	H	H	$\downarrow$	$\overline{Q}_n$	Q_n	TOGGLE
H	X	X	$\uparrow$	Q_n	$\overline{Q}_n$	NO CHANGE

X : Don't Care

IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 25	mA
DC V_{CC} / Ground Current	I_{CC}	± 50	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	°C

*500mW in the range of $T_a = -40^\circ\text{C} \sim 65^\circ\text{C}$. From $T_a = 65^\circ\text{C}$ to 85°C a derating factor of $-10\text{mW}/^\circ\text{C}$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	$2 \sim 6$	V
Input Voltage	V_{IN}	$0 \sim V_{CC}$	V
Output Voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating Temperature	T_{opr}	$-40 \sim 85$	°C
Input Rise and Fall Time	t_r, t_f	$0 \sim 1000$ ($V_{CC} = 2.0\text{V}$) $0 \sim 500$ ($V_{CC} = 4.5\text{V}$) $0 \sim 400$ ($V_{CC} = 6.0\text{V}$)	ns

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40 \sim 85^\circ\text{C}$		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	V_{IL}		2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	0.50 1.35 1.80	V
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20\mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	V
			$I_{OH} = -4 \text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	
			$I_{OH} = -5.2 \text{ mA}$	6.0	5.68	—	—	—	
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20\mu\text{A}$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	V
			$I_{OL} = 4 \text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	
			$I_{OL} = 5.2 \text{ mA}$	6.0	—	—	—	0.33 0.33	
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC} \text{ or GND}$	6.0	—	—	± 0.1	—	± 1.0	μA
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC} \text{ or GND}$	6.0	—	—	2.0	—	20.0	

TIMING REQUIREMENTS (Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C		Ta = -40~85°C		UNIT
				TYP.	LIMIT	LIMIT		
Minimum Pulse Width (CK)	$t_{W(L)}$ $t_{W(H)}$		2.0	—	75	95	ns	
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Pulse Width (CLR)	$t_{W(L)}$		2.0	—	75	95		
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Set-up Time	t_s		2.0	—	75	95		
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Hold Time	t_h		2.0	—	0	0		
			4.5	—	0	0		
			6.0	—	0	0		
Minimum Removal Time (CLR)	t_{rem}		2.0	—	25	30		
			4.5	—	5	6		
			6.0	—	5	5		
Clock Frequency	f		2.0	—	6	5	MHz	
			4.5	—	31	25		
			6.0	—	37	30		

AC ELECTRICAL CHARACTERISTICS ($C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, Ta = 25°C, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t_{TLH} t_{THL}		—	4	8	ns
Propagation Delay Time (CK—Q, $\bar{Q}$)	t_{PLH} t_{PHL}		—	11	21	
Propagation Delay Time (CLR—Q, $\bar{Q}$)	t_{PLH} t_{PHL}		—	12	24	
Maximum Clock Frequency	f_{MAX}		34	75	—	MHz

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	t_{TLH} t_{THL}		2.0	—	30	75	—	95	ns
			4.5	—	8	15	—	19	
			6.0	—	7	13	—	16	
Propagation Delay Time (CK—Q, $\bar{Q}$)	t_{PLH} t_{PHL}		2.0	—	48	125	—	155	
			4.5	—	14	25	—	31	
			6.0	—	12	21	—	26	
Propagation Delay Time (CLR—Q, $\bar{Q}$)	t_{PLH} t_{PHL}		2.0	—	52	140	—	175	
			4.5	—	15	28	—	35	
			6.0	—	13	24	—	30	
Maximum Clock Frequency	f_{MAX}		2.0	6	23	—	5	—	MHz
			4.5	31	70	—	25	—	
			6.0	37	80	—	30	—	
Input Capacitance	C_{IN}			—	5	10	—	10	pF
Power Dissipation Capacitance	C_{PD} (1)			—	33	—	—	—	

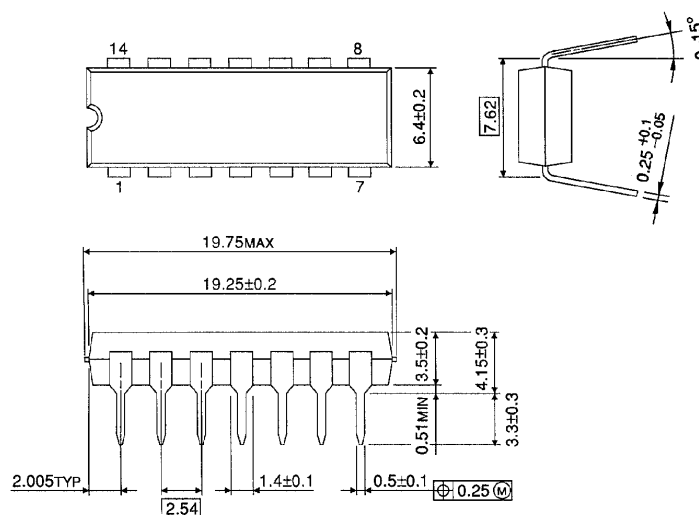
Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 2 \text{ (per F/F)}$$

DIP 14PIN PACKAGE DIMENSIONS (DIP14-P-300-2.54)

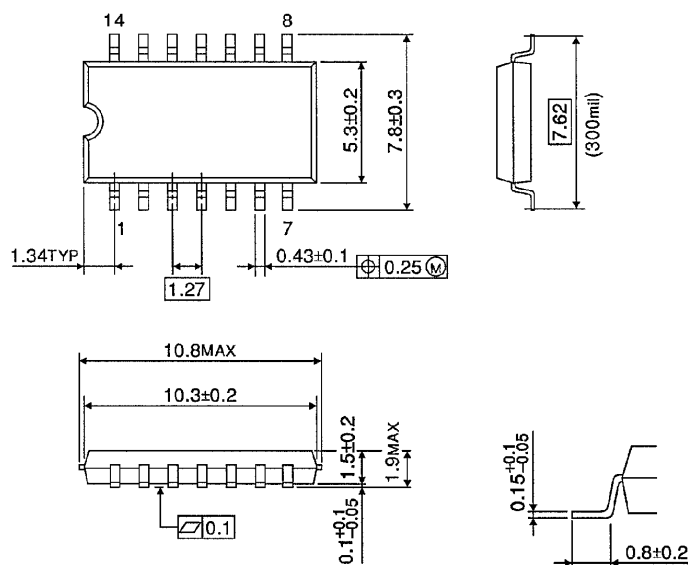
Unit in mm



Weight : 0.96g (Typ.)

SOP 14PIN (200mil BODY) PACKAGE DIMENSIONS (SOP14-P-300-1.27)

Unit in mm

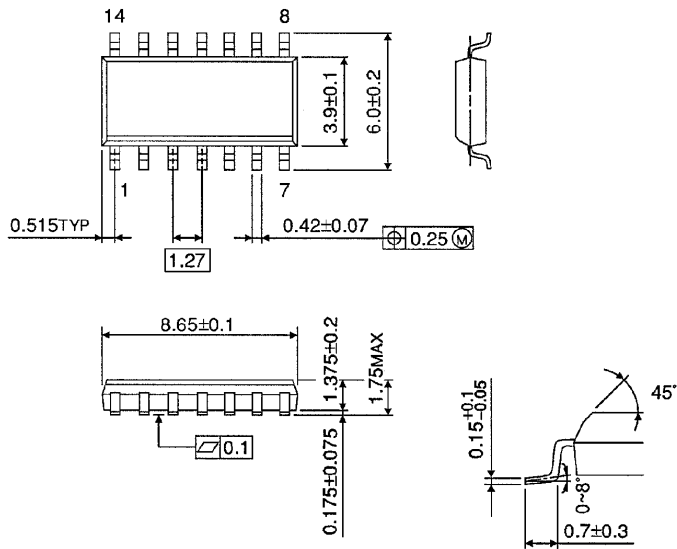


Weight : 0.18g (Typ.)

SOP 14PIN (150mil BODY) PACKAGE DIMENSIONS (SOL14-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.12g (Typ.)

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